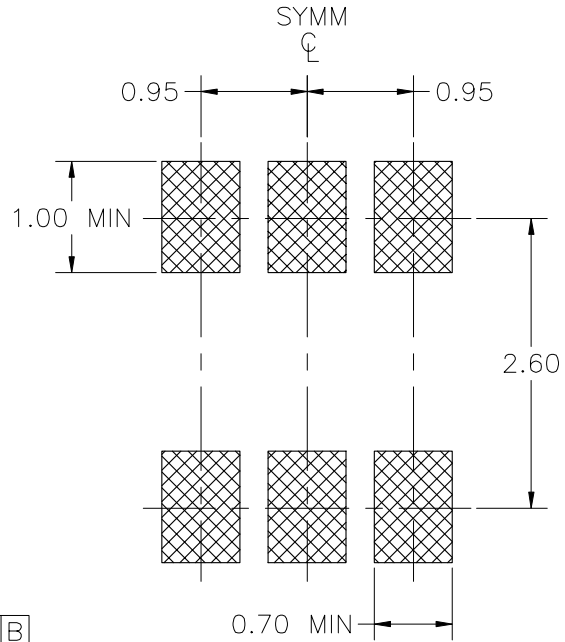
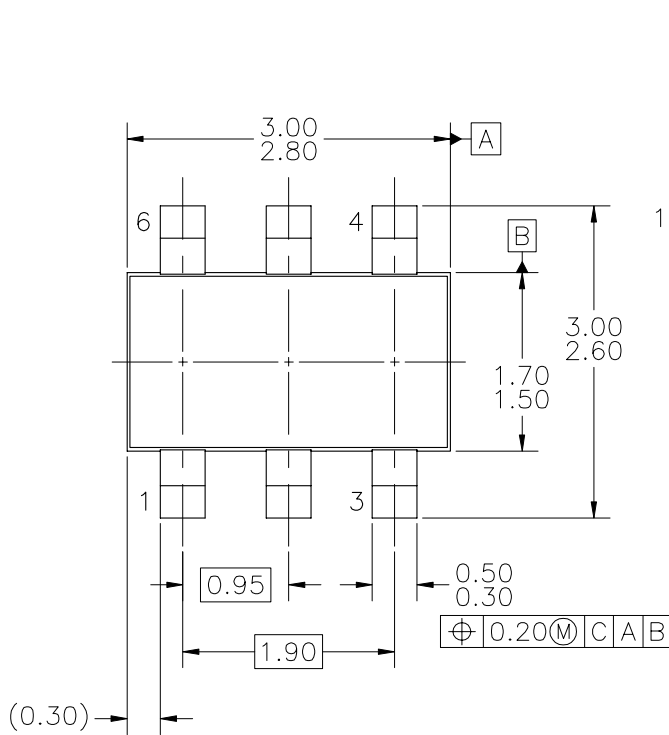
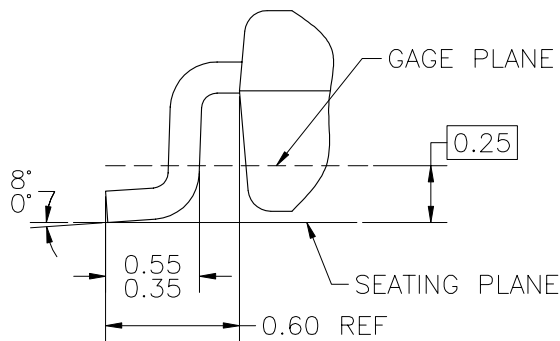
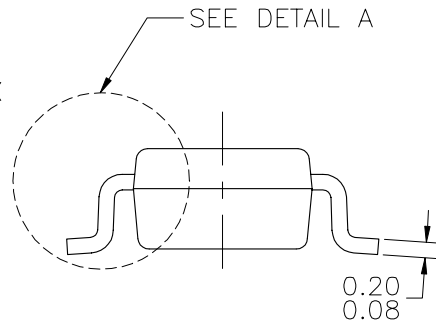
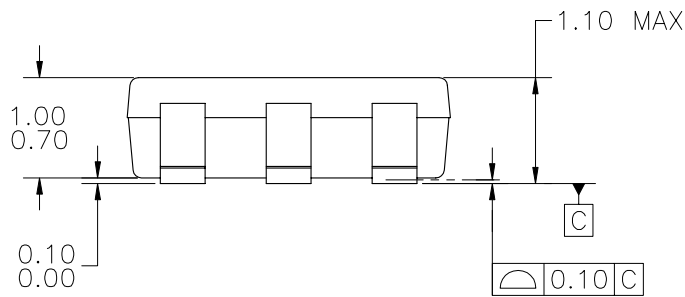


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REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL		11209 07/18/96	LUA
B	REDRAW AS PER STANDARD DRAWING TEMPLATE	02799	05/19/99	MRG
C	CHG TOTAL PKG THICKNESS FR 0.95-1.40 TO 1.10 MAX; CHG PKG THICKNESS FR 0.90-1.25 TO 0.70-1.00. CHG PROFILE HEIGHT FR 0.05-0.15 TO 0.00-0.10; CHG FOOT LANDING ANGLE FR 0-10° TO 0-8°; CHG GAGE PLANE FR 0.20 TO 0.25; REFLECT MO-193 VAR AA.	CB/068/00	APR.17.2000	MRG/GSB
D	REMOVED NOTE C) STANDARD LEAD FINISH: 150 MICRONS (3.81 MICROMETERS) MIN. TIN/LEAD (SOLDER) ON COPPER.	CB/149/05	17OCT2005	ER



LAND PATTERN RECOMMENDATION



DETAIL A
SCALE: 50X

NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC MO-193. VAR. AA, ISSUE C, DATED JANUARY 2000.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.

MA06AREVD

APPROVALS		DATE	FAIRCHILD SEMICONDUCTOR™	
DRAWN: J. GOMEZ		17OCT2005	CEBU PHILIPPINES	
CHECKED: E. ROSAL			MOLDED PACKAGE SUPERSOT, 6 LEADS, (MARKETING OUTLINE)	
APPROVED: M.R. GESTOLE				
G.S. BAJE			SCALE 25:1	SIZE A3
PROJECTION			DRAWING NUMBER MKT-MA06A	REV D
FORMERLY: N/A			SHEET : 1 OF 1	